

Title (en)
DUAL CMP PAD CONDITIONER

Title (de)
DOPPEL-ABRICHTVORRICHTUNG FÜR POLIERKISSEN

Title (fr)
DOUBLE DISPOSITIF DE CONDITIONNEMENT POUR TAMPONS DE POLISSAGE CHIMIQUE ET MECANIQUE

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Application
EP 00919823 A 20000329

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Abstract (en)
[origin: WO0060645A2] According to an example embodiment, the present invention is directed to a CMP polishing apparatus having at least two conditioning arms for use in conditioning a polishing pad. The CMP polishing apparatus includes a first pad conditioner configured and arranged both to dispense slurry and to condition the pad. A second pad conditioner is configured and arranged both to clean a portion of the polishing pad and to dispense cleaning chemicals. Benefits of using this embodiment include enhanced pad cleaning, better slurry dispense, improved wafer quality, and faster production.
[origin: WO0060645A2] According to an example embodiment, the present invention is directed to a CMP polishing apparatus (100) having at least two conditioning arms (110+120) for use in conditioning a polishing pad (150). The CMP polishing apparatus includes a first pad conditioner (130) configured and arranged both to dispense slurry and to condition the pad. A second pad conditioner (140) is configured and arranged both to clean a portion of the polishing pad (150) and to dispense cleaning chemicals. Benefits of using this embodiment include enhanced pad cleaning, better slurry dispense, improved wafer quality, and faster production.

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